MA3X701 (MA10701)

Silicon epitaxial planar type

For high frequency rectification

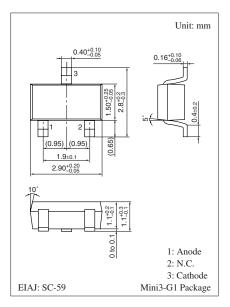
■ Features

• Forward current (Average) $I_{F(AV)} = 700 \text{ mA}$ rectification is possible

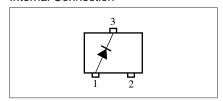
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V _{RRM}	30	V
Forward current (Average)	I _{F(AV)}	700	mA
Non-repetitive peak forward surge current *	I_{FSM}	5	A
Junction temperature	T _j	125	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



Marking Symbol: M4P
Internal Connection



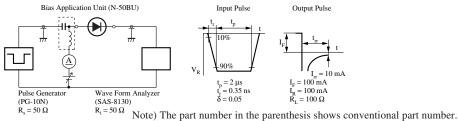
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F}	$I_Z = 700 \text{ mA}$			0.55	V
Reverse current	I_R	$V_R = 30 \text{ V}$			80	μΑ
Terminal capacitance	C _t	$V_R = 0 V, f = 1 MHz$		120		pF
Reverse recovery time *2	t _{rr}	$I_F = I_R = 100 \text{ mA}$		7.5		ns
		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				
Thermal resistace (j-a)	R _{th(j-a)1}			420		°C/W
	R _{th(j-a)2} *1			330		°C/W

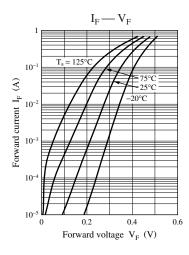
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

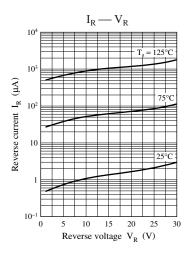
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 400 MHz.
- 4. *1: Guaranteed on the condition of soldered to PC board. (Cu foil 0.8 mm × 20 mm)

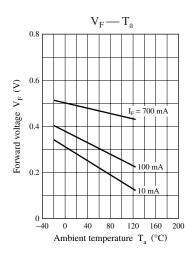
*2: t_{rr} measurement circuit

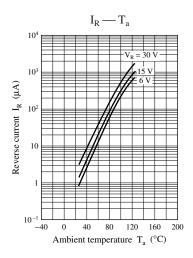


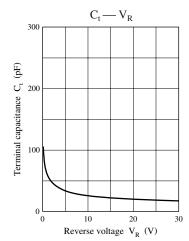


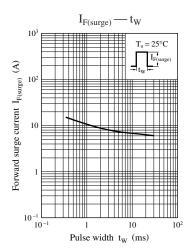












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